Version With Markings To Show Changes Made

1. (Twice Amended) An electronic assembly comprising:

[a semiconductor die] a substrate having a plurality of electrically conductive terminals; and

a plurality of resilient, springable, free-standing interconnection elements, each of the interconnection elements having [a die] an end attached directly to a respective one of the terminals on the [die] substrate, an elongate section between the [die] attached end and a contact end, and a tip on the contact end, the tip pointing away from the [die] substrate, wherein the interconnection elements include a precursor element and an overcoat material covering said precursor element, the precursor element is of a flexible, substantially non-resilient material and the overcoat material provides the resilient springability of the interconnection element.

123. (Amended) An electronic assembly comprising:

[a semiconductor die] a substrate having a plurality of electrically conductive terminals; and

a plurality of resilient, springable, free-standing interconnection elements, each of the interconnection elements including a precursor element of a flexible, non-resilient material and an overcoat material covering said precursor element, the overcoat material providing the resilient springability of the interconnection element, and having

[a die] an end attached directly to a respective one of the terminals on the [die] substrate,

an elongate section extending from the [die] attached end to a contact end, the elongate section including at least a first bend and a second bend, and

a tip on the contact end, the tip pointing away from the [die] substrate.

124. (Amended) An electronic assembly comprising:

[a semiconductor die] a substrate having a plurality of electrically conductive terminals; and

a plurality of resilient, springable, free-standing interconnection elements, each of the interconnection elements having [a die] an end attached directly to a respective one of the terminals on the [die] substrate, an elongate section between the [die] attached end and a contact end, and a tip on the contact end, wherein the interconnection elements include a precursor element and an overcoat material covering said precursor element, the precursor element is of a flexible, substantially non-resilient material and the overcoat material provides the resilient springability of the interconnection element.

127. (Amended) The electronic assembly of claim 126 wherein the elongate section includes a proximate portion extending from said [die] substrate end at an angle away from the [die] substrate, a mid-portion extending at an angle from said proximate portion, and a distal portion extending at an angle from said mid-portion and away from the [die] substrate.

128. (Amended) The electronic assembly of claim 127 wherein the proximate portion extends from the [die] substrate end at an angle substantially perpendicular to the [die] substrate.

130. (Amended) The electronic assembly of claim 129 wherein the contact end is moveable toward the surface of the [die] substrate upon the application of a downward pressure upon the tip.

131. (Amended) The electronic assembly of claim 124 wherein the assembly further comprises a ~~second~~ substrate having a plurality of contacts, and at least one of the interconnection elements conducts electricity when the tip of the interconnection [elements] element is in releasable contact with a respective contact on the second substrate.